

Title (en)  
ASSEMBLY DEVICE

Title (de)  
MONTAGEVORRICHTUNG

Title (fr)  
DISPOSITIF DE MONTAGE

Publication  
**EP 1118104 A1 20010725 (DE)**

Application  
**EP 00951498 A 20000811**

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Abstract (en)  
[origin: EP1076357A1] The invention relates to an assembly device (10), especially a fully automatic assembly device for producing microsystem technical products and for assembling components in the semiconductor industries. Said assembly device comprises an assembly table (12), at least one material transport system (32) that transports the products to be placed with components, and at least one transport system (16) that is mounted on the assembly table (12). The device is further provided with a component transport unit (28) with at least one assembly head (30). Said component transport unit(s) (28) is/are mounted on one or more carrier system(s) (20) that is/are displaced in parallel to the direction of transport of the products to be placed with components which products are in turn displaced by the material transport system(s) (32). The material transport system (32) consists of at least two individual transport systems (34, 36, 38, 40, 42, 44) that run parallel. Every individual transport system (34, 36, 38, 40, 42, 44) is provided with separately controlled drive systems (46, 48, 50, 52, 54, 56). The assembly device (10) has at least one information memory for receiving and processing component-specific data of a multitude of components in a component reservoir (58) and of data with respect to their position within the component reservoir (58). The component transport unit(s) (28) and/or the assembly table (12) are controlled on the basis of these data.

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